



8-Bit Single-Chip Microcontroller

Overview

The LC86P5032 microcontroller, a new addition to the LC865000 series, is a 8-bit single chip CMOS microcontroller with one-time PROM.

This microcontroller has the same function and pin assignment as for the LC865000 series mask ROM version, and a 32K-byte PROM.

The same DIP/QFP packages as for the LC865000 series are available for shipment. It is suitable for setting up the first release, for prototyping and developing and testing applications.

Features

- (1) Option switching using PROM data
 - The optional functions of the LC865000 series can be specified using PROM data.
 - The functions of the trial products can be evaluated using a mass production board.
- (2) Internal one-time PROM capacity
- (3) Internal RAM capacity : 512 bytes

Mask ROM version	PROM capacity	RAM capacity
LC865032	32512 bytes	512 bytes "
LC865028	28672 bytes	512 bytes
LC865024	24576 bytes	512 bytes
LC865020	20480 bytes	384 bytes
LC865016	16384 bytes	384 bytes
LC865012	12288 bytes	384 bytes
LC865008	8192 bytes	384 bytes

(4) Operating supply voltage(5) Instruction cycle time

: 4.5 to 6.0 V : 0.98 to 400 μs

(6) Operating temperature range

: 0.98 to 400 μs : -30°C to +70°C

32768 bytes

(7) Pins and package compatible with the mask ROM version
(8) Applicable mask version : LC865032/LC8

: LC865032/LC865028/LC865024/LC865020/LC865016/LC865012, LC865008

(9) Factory shipment

: DIP-64S QFP-64E

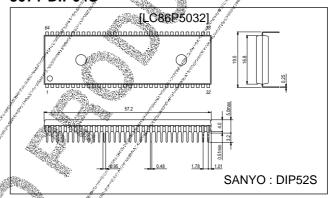
Programming service

We offer various services at nominal charges. These include ROM writing, ROM reading, and package stamping and screening. Contact our local representatives for further information.

Package Dimensions

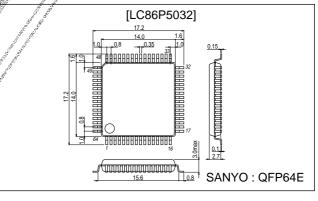
unit: mm

3071-DIP64S



unit ; mm

3159-QFP64E



Usage Notes

When using, please take note of the following.

(1) Differences between the LC86P5032 and the LC865000 series

Item	LC86P5032	LC865632/28/24/20/16/12/08
Port status at reset	Please refer to "Port status at reset" on the next p	page.
Operation after releasing reset	The option is specified by degrees within 3 ms after applying a 'H' level to the reset pin. The program located at 00H is executed.	The program located at 00H is executed immediately after applying a 'H' level to the reset pin.
Operating voltage range (VDD)	4.5 to 6.0 V	2.7 to 6.0 V
Total output current [∑loah(1)] [∑loah(1)]		
Current drain [IDDOP(1)] [IDDOP(2)] [IDDOP(3)] [IDDOP(4)]	Refer to 'Electrical Characteristics' on the semico	nductor news.

• LC86P5032 Options

Option	Pins, Circuits	Option Settings
Configuration of input/output ports	Port 0	1 Input : No pull-up MOS transistor
	(Can be specified for	Output : N-channel open drain
	each bit.)	2. Input : Pull-up MOS transistor
	// 🕺	Output CMOS
	Ports 1, 2	1. 16put No programmable pull-up MOS transistor
	(Can be specified for	Output : N-channel open drain
	each bit.)	2. Input : Programmable pull-up MOS transistor
		Output : CMOS
	Ports 3, 4, 5	1. Input : No programmable pull-up MOS transistor
<i>j</i>	(Can be specified for	Output: N-channel open drain
A STATE OF THE STA	each bit.)	2. Input : Programmable pull-up MOS transistor
		Output : CMOS
Port 7 pull-up MOS transistor	Port-7	Pull-up MOS transistor not provided
A STATE OF THE STA	(Can be specified for	Pull-up MOS transistor provided
	each bit.)	*P74 has no pull-up resistor option.

The port operation related to the option is different at reset. Please refer to the next table.

• Port configuration at reset

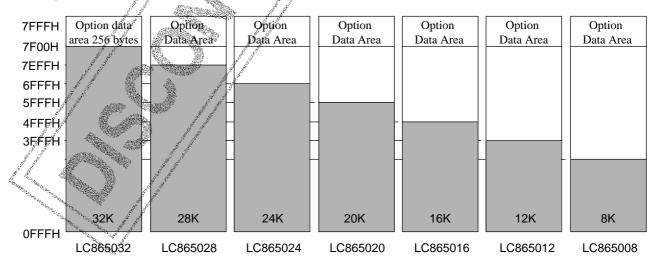
Pin	Option settings	LC86P5032	LC865032/28/24/20/16/12/08
P0	Input : No pull-up MOS transistor Output : N-channel open drain	(Same as for the mask version)	Input mode without pull-up MOS transistor (Output is OFF)
	Input : Pull-up MOS transistor Output : CMOS	Input mode • The Pull-up MOS transistor is not present during reset or several hundred microseconds after releasing reset. After that, the pull-up MOS transistor is present. (Output is OFF)	Input mode with pull-up MOS transistor (Output is OFF)
P1, P2	Input : Programmable pull-up MOS transistor Output : N-channel open drain	(Same as for the mask version)	Input mode without pull-up MOS transfer (Output is ØFF)
	Input : Programmable pull-up MOS transistor Output : CMOS	(Same as for the mask version)	Input mode without pull-up MOS transister (Output is OFF)
P3, P4, P5	Input : Non-Programmable pull-up MOS transistor Output : N-channel open drain	(Same as for the mask version)	Input mode without pull-up MOS transistor (Output is OFF)
	Input : Programmable pull-up MOS transistor Output : CMOS	(Same as for the mask version)	Input mode without pull-up MOS transistor (Output is OFF)
P7	Pull-up MOS transistor not provided	(Same as for the mask version)	Input mode without pull-up MOS transistor
	Pull-up MOS transistor provided	Input mode • The pull-up MQS transister is not present during reset or several hundred microseconds after releasing reset. After that, the pull-up MQS transistor is present.	Input mode with pull-up MOS transistor

(2) Option

The LC86P5032 uses 256 bytes addressed 7F00H to 7FFFH in program memory as option data area. This area does not affect the execution of the program but means that the LC865032 program memory is 32512 bytes addressed 0000H to 7EFFH.

The option data is written using the option specifying program "\$U865000. EXE". The option data is linked to the program area by linkage loader "L865000. EXE".

(3) ROM space



(4) Ordering information

1. When ordering identical mask ROM and PROM devices simultaneously.

Provide an EPROM containing the target memory contents together with separate order forms for each of the mask ROM and PROM versions.

2. When ordering a PROM device.

Provide an EPROM containing the target memory contents together with an order form.

How to Use

(1) Specification of options

Programming data for the LC86P5032's EPROM is required.

The debugged evaluation file (EVA file) must be converted to an INTEL-HEX formatted file (HEX file) with file converter program EVA2HEX.EXE. The HEX file is used as the programming data for the LC86P5032

(2) How to program the EPROM

The LC86P5032 can be programmed by an EPROM programmer with attachments W86EP5032D and W86EP5032Q.

• Recommended EPROM programmer

Supplier	EPROM programmer
Advantest	R4945, R4944, R4943
Andou	AF-9704
AVAL	PKW-1100, PKW-3000
Minato Electronics	MODÉL 1890A

• "27512 (Vp-p = 12.5 V) Intel high-speed programming" mode available. The address must be set to "0000H to 7FFFH" and the jumper (DASEC) must be set 'OFF, at programming.

(3) How to use the data security function

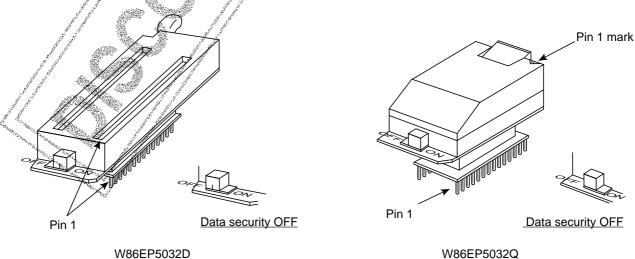
"Data security" is a function to prevent EPROM data from being read-

Instructions on using the data security function

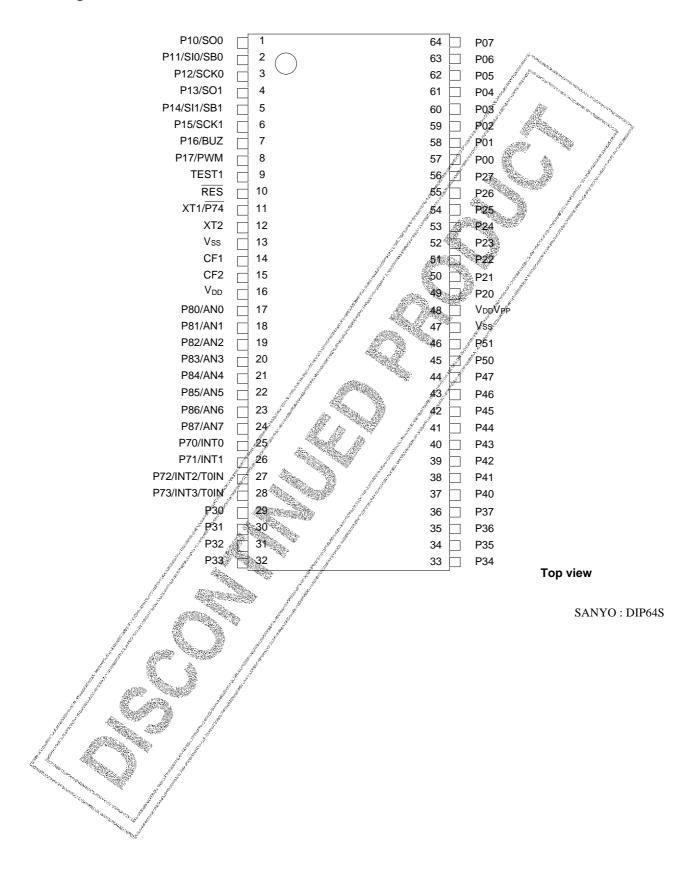
- Set the jumper of attachment 'ØN'.
 Attempt to program the EPROM. The EPROM programmer will display an error. The error indication is a result of normal activity of the data security feature. This is not a problem with the EPROM programmer chip.

Notes

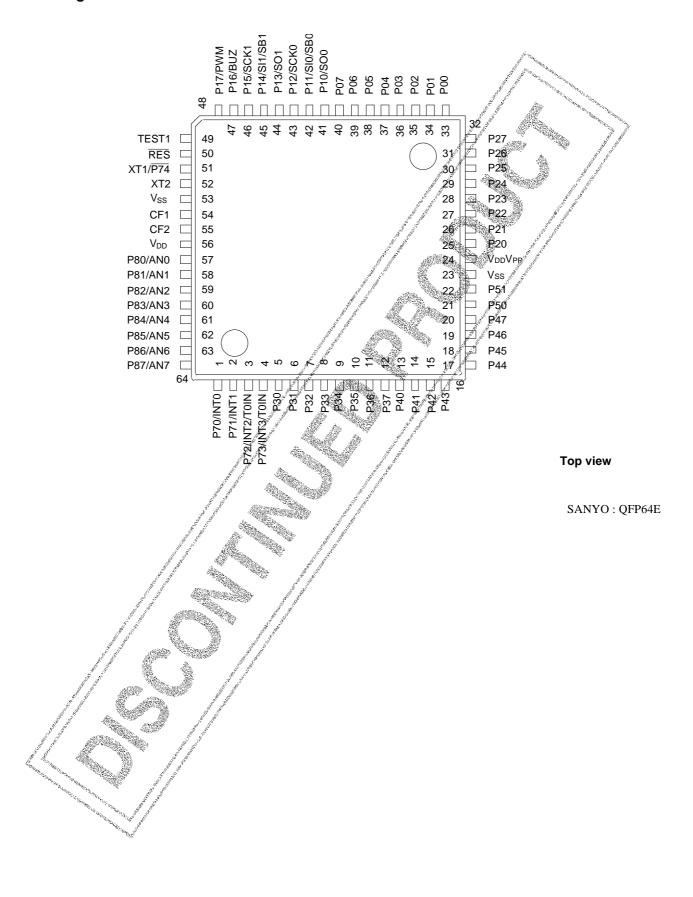
- The data security function is not carried out when the data of all addresses contain 'FF' at step 2 above.
- Data security cannot be executed when the sequential operation "BLANK=>PROGRAM=>VERIFY" is used at step 2 above.
- · Set the jumper 'OFF' after execution of data security.



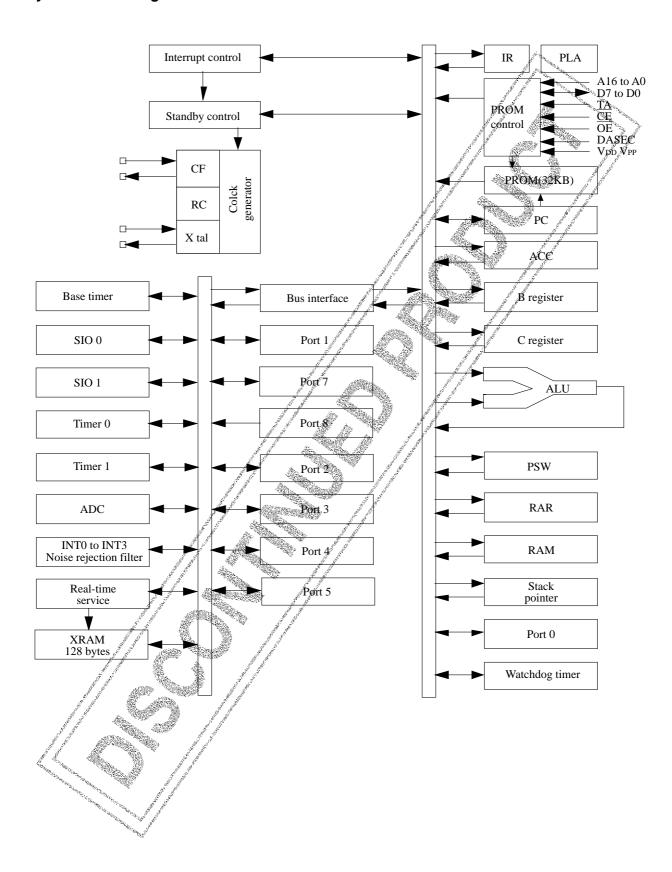
Pin Assignment



Pin Assignment



System Block Diagram

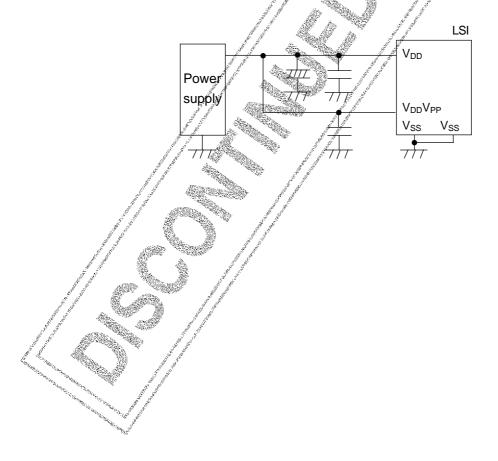


LC86P5032 Pin Description

Pin name	I/O	Funct	ion descrip	otion		Opt	tion	Function in PROM mode
Vss		Power supply pir	n(-)					8 th 10 _{th}
V _{DD}		Power supply pir	n(+)					
$V_{DD}V_{PP}$		Power supply pir	n(+)				y proper	Power for programming
PORT0 P00 to P07	I/O	8-bit input/outp Input for port 0 Input/output in Input for HOLD	interrupt nibble units	5		Pull-up resis Present/NotOutput form N-channel o	present : CMOS/	
PORT1 P10 to P17	I/O	8-bit input/outp Data direction c Other pin functi P10 : SIO0 dat P11 : SIO0 clo P13 : SIO1 dat P14 : SIO1 dat P15 : SIO1 clo P16 : Buzzer o P17 : Timer 1 ce	an be spec ons a output a input/bus ck input/ou a output a input/ bu ck input/ou utput	s input/outp ttput s input/outp ttput	h bit. ut	Output form, N-channel op		Data input/output Do to D7
PORT2 P20 to P27	I/O	8-bit input/outp Data direction c	•	ified for eac		Output form : N-channel or		
PORT3 P30 to P37	I/O	8-bit input/outp Data direction c 15 V withstand	an be spec		h bit.	Output form N-channel op		Address input • A7 to A0
PORT4 P40 to P47	I/O	8-bit input/outpData direction c15 V withstand	an be spec	2000	17,000,000	Output form : N-channel op		Address input • A14 to A8 (*5) • P47 : TA (*4)
PORT5 P50 to P51	I/O	2-bit input/outData direction c15 V withstand	an be spec			Output form : N-channel op		
PORT7 P70 P71 to P74	I/O	• 5-bit input por • Other pin func P70 INTO input Tr. output P71 : INT 1 input P72 : INT 2 input P73 : INT 3 input	tions HOLD rele for watchd /HOLD rele /timer 0 ev	og timer. ease, ent input.	nnel	Pullup resistor Present/Not p (P70, 71, 72, * P74 has no resistor.	oresent 73)	Input of PROM control signal • DASEC (*1) • OE (*2) • CE (*3)
And a		event input P74 Input pin X oscillation Interrupt receiv	ut. T1 for 32.7	768 kHz cry	stal		Vector	
		INTO Enable	Enable	falling Disable	Enable		03H	
Canada Carana		INT1 Enable	Enable	Disable	Enabl		0BH	
1000	Allen.	INT2 Enable	Enable	Enable	Disabl		13H	
***************************************	Sales Sa	NT3 Enable	Enable	Enable	Disabl		1BH	

Pin name	I/O	Function description	Option	Function in PROM mode
PORT8 P80 to P87	I	8-bit input port Other functions AD input port (8 port pins)		
RES	1	Reset pin		
TEST1	0	Test pin Should be left open.	ge ^d and see	
XT1/P74	I	Input pin for 32.768 kHz crystal oscillation Other function : Input port P74 When not used, connect to V _{DD} .	p de p de la companya della companya de la companya de la companya della companya	
XT2	0	Output pin for 32.768 kHz crystal oscillation When not used, should be left open.		
CF1	I	Input pin for ceramic resonator oscillation		1
CF2	0	Output pin for ceramic resonator oscillation		

- All port options can be specified in bit units.
- *1 Memory select input for data security
- *2 Output enable input
- *3 Chip enable input
- *4 TA → PROM control signal input *5 A14 → Address input
- \bullet Connect as shown in the following figure to reduce noise into $V_{DD}\,\text{pin}.$ Short-circuit the V_{DD} pin to the $V_{DD}V_{PP}$ pin. Short-circuit the V_{SS} pin to the V_{SS} pin.



1. Absolute Maximum Ratings at $Ta = 25^{\circ}C$, $V_{SS} = 0$ V

Parame	ter	Symbol	Pins	Conditions			Ratings		Unit
					V _{DD} [V]	min	typ	max	
Supply volt	age	V _{DD} max	VDD, VDDVPP	$V_{DD} = V_{DD}V_{PP}$		-0.3 🖋	Nice of the Parket	+7.0	V
Input voltag	je	V _I (1)	• Ports 71, 72, 73, 74 • Port 8 • RES			-0:3/		Vpp+0.3	
Input/outpu voltage	t	V _{IO} (1)	• Ports 0, 1, 2 • Ports 3, 4, 5 of CMOS output		and the second s	-0.3		, V _{DD} +0,3	j.
		V _{IO} (2)	Ports 3, 4, 5 of open- drain output	<u>j</u> d		-0.3		15	
High- level output	Peak output current	Іорн(1)	Ports 0, 1, 2, 3, 4, 5	CMOS output At each pin		4		à.	mA
current	Total output	∑l _{OAH} (1)	Ports 0, 1, 2	Total of all pins		–25 A	g g g g g g g g g g g g g g g g g g g		
	current	Σloah(2)	Ports 3, 4, 5	Total of all pins		<i>_</i> -20			
Low- level	Peak output	I _{OPL} (1)	Ports 0, 1, 2, 3, 4, 5	At each pin	1			20	
output current	current	I _{OPL} (2)	Port 70	At each pin				15	
	Total	Σ loal(1)	Ports 0, 1, 70	Total of all pins				40	
	output current	Σ loal(2)	Port 2	Total of all pins				40	
	Carront	$\Sigma I_{OAL}(3)$	Ports 3, 4, 5	Total of all pins	J.			80	
Power dissi	ipation	Pd max(1)	DIP64S	Ta = -30°C+70°C /				720	mW
(max.)		Pd max(2)	QFP64E	Ta.= -30°C+70°Ç [∕]				420	
Operating temperature	e range	Topr				-30		70	°C
Storage temperature	e range	Tstg				-65		150	

2. Recommended Operating Range at Ta = $-30^{\circ}C$ to $+70^{\circ}C$, V_{SS} = 0 V

Parameter	Symbol	Pins	Conditions			Rating	gs	Unit
				V _{DD} [V]	min	typ	max	
Operating voltage range	V _{DD} (1)	V _{DD}	0.98 μs ≤ tCYC tCYC ≤ 400 μs		4.5	Part Control	6.0	V
HOLD voltage	V_{HD}	V _{DD}	RAM and registers retain their pre-HOLD mode values.	34.0	2.0		6.0	
Input high voltage	V _{IH} (1)	Port 0 (Schmitt)	Output disabled	4.5 to 6.0	0.4 √ pd +0.9		y de	ř
	V _{IH} (2)	• Ports 1, 2 • Ports 72, 73 (Schmitt)	Output disabled	4.5 to 6.0	0. 75√ _{₽D}		V_{DD}	
	V _{IH} (3)	Port 70 Port input/interrupt. Port 71 RES (Schmitt)	Output N-channel transistor OFF	4.5 10 6.0	0.75V _{DD}		V _{DD}	
	V _{IH} (4)	Port 70 Watchdog timer	Output N-channel transistor OFF	4.5 to 6.0	0,9V _{DD}		V_{DD}	
	V _{IH} (5)	• Port 74 • Port 8	Output N-channel transistor OFF	4 .5 to 6.0	0.75V _{DD}		V_{DD}	
	V _{IH} (6)	Ports 3, 4, 5 of CMOS output (Schmitt)	Output disabled	4.5 to 6.0	0.75V _{DD}		V _{DD}	
	V _{IH} (7)	Ports 3, 4, 5 of open drain output (Schmitt)	Output disabled	4.5 to 6.0	0.75V _{DD}		13.5	
Input low	V _{IL} (1)	Port 0 (Schmitt)	Output disabled /	4.5 to 6.0	Vss		$0.2V_{DD}$	
voltage	V _{IL} (2)	• Ports 1, 2, 3, 4, 5 • Ports 72,73 (Schmitt)	Supput disabled	4.5 to 6.0	V _{SS}		0.25V _{DD}	
	VIL(3)	Port input/interrupt. Port 71 RES (Schmitt)	N-channel transistor	4.5 to 6.0	Vss		0.25V _{DD}	
	¥ı∟(4)	Port 70 Watchdog timer	N-channel transistor OFF	4.5 to 6.0	Vss		0.8V _{DD} -1.0	
g general section of the section of	V _{IL} (5)	• Port 74 • Port 8	N-channel transistor OFF	4.5 to 6.0	V _{SS}		0.25V _{DD}	
Operation cycle time	tCYC			4.5 to 6.0	0.98		400	μs

Parameter	Symbol	Pins	Conditions			Ratings	6	Unit
				V _{DD} [V]	min	typ	max	
Oscillation frequency range (Note 1)	FmCF(1)	CF1, CF2	12 MHz (ceramic resonator oscillation).Refer to Figure 1.	4.5 to 6.0	11.76	12	12.24	MHz
	FmCF(2)	CF1, CF2	 3 MHz (ceramic resonator oscillation). Refer to Figure 1.	4.5 to 6.0	2.94	, g	3.06	**************************************
	FmRC		RC oscillation	4.5 to 6.0	0.4	0.8	2.0	1
	FsXtal	XT1, XT2	• 32.768 kHz (crystal oscillation). • Refer to Figure 2.	4.5 to 6.0		32.768	A STATE OF THE STA	kHz
Oscillation stable time period (Note 1)	tmsCF(1)	CF1, CF2	12 MHz (ceramic resonator oscillation). Refer to Figure 3.	4.5 to 6.0		0.03	0.5	ms
	tmsCF(2)	CF1, CF2	3 MHz (ceramic resonator oscillation). Refer to Figure 3.	4.5 to 6.0		0.2	2	
	tssXtal	XT1, XT2	32.768 kHz (crystal oscillation). Refer to Figure 3.	4.5 to 6.0		1	1.5	S

(Note 1) The oscillation constants are shown on Table 1 and Table 2.



3. Electrical Characteristics at $Ta{=}\,{-}30^{\circ}C$ to ${+}70^{\circ}C$, V_{SS} = 0 V

Parameter	Symbol	Pins	Conditions			Ratings		Unit
				V _{DD} [V]	min 🎤	typ	max	
Input high current	Ін(1)	Ports 3, 4, 5 at open-drain output	Output disabled V _{IN} = 13.5 V (including off-state leak current of output transistor)	4.5 to 6.0			5	μA
	Ін(2)	•Port 0 without pull-up MOS transistor •Ports 1, 2, 3, 4, 5	Output disabled Pull-up MOS transistor OFF. V _{IN} = V _{DD} (including off-state leak current of output transistor)	4.5 to 6.0			1	
	I _{IH} (3)	•Ports 70, 71, 72, 73 without pull-up MOS transistor •Port 8	VIN = VDD	A.5 to 6.0			1	
	I _{IH} (4)	•RES	VIN = VDD	4.5 to 6.0			1	
Input low current	l _{IL} (1)	•Ports 1, 2, 3, 4, 5 •Port 0 without pull-up MOS transistor	Output disabled Pull-up MOS transistor OFF, Vin = Vss (including off-state teak current of output transistor)	4	1/1			
	I _{IL} (2)	•Ports 70, 71, 72, 73 without pull-up MOS transistor •Port 8	V _N = V _{SS}	4.5 to 6.0	-1			
	I _{IL} (3)	•RES	V _{EN} F V _{SS}	4.5 to 6.0	-1			
Output high voltage	V _{OH} (1)	•Ports 0, 1, 2, 3, 4, 5 at CMQS output	I _{0H} = -1.0 mA	4.5 to 6.0	V _{DD} –1			V
	V _{OH} (2)	// %	lo⊮⊭ –0.1 mA	4.5 to 6.0	V _{DD} -0.5			
Output low	V _{OL} (1)	Ports 0, 1, 2, 3, 4, 5	loL = 10 mA	4.5 to 6.0			1.5	
voltage	V _{OL} (2)		I _{OL} = 1.6 mA	4.5 to 6.0			0.4	
	V _{OL} (3)	Port 70	lou = 1 mA	4.5 to 6.0			0.4	
	V _{OL} (4)		/o _k = 0.5 mA	4.5 to 6.0			0.4	
Pull-up MOS transistor resistance	Rou P	•Ports 0, 1, 2, 3, 4, 5 •Ports 70, 71, 72, 73	VoH = 0.9 VDD	4.5 to 6.0	15	40	70	kΩ
Hysteresis voltage	VHIS	• Ports 0, 1, 2, 3, 4, 5 • Ports 70, 71, 72, 73 • RES	Output disable	4.5 to 6.0		0.1V _{DD}		V
Pin capacitance	CP.	All pins,	•f = 1 MHz •Unmeasured input pins are set to Vss level. •Ta = 25°C	4.5 to 6.0		10		pF

4. Serial Input/Output Characteristics at $Ta=-30^{\circ}C$ to $+70^{\circ}C$, $~V_{SS}=0~V$

F	Paran	neter	Symbol	Pins	Conditions			Rating	s	Unit
						V _{DD} [V]	min	typ	max	
		Cycle	tCKCY(1)	SCK0, SCK1	Refer to Figure 5.	4.5 to 6.0	2	f gallen		tCYC
	Input clock	Low- level pulse width	tCKL(1)			4.5 to 6.0	1.86			
ock	диI	High- level pulse width	tCKH(1)			4.5 to 6.0	1.5			
Serial clock		Cycle	tCKCY(2)	SCK0, SCK1	Use pullup resistor (1 kΩ) when set to open-drain output.	4.5 to 6.0	2			
	Output clock	Low- level pulse width	tCKL(2)		• Refer to Figure 5/	4.5 to 6.0		1/2tcKYC		
	0	High- level pulse width	tCKH(2)			4.5 to 6.0		1/2tCKYC		
nput	Data time	setup	tICK	• SI0, SI1 • SB0, SB1	• Data set-up to SCK0, 4	4.5 to 6.0	0.1			μs
Serial input	Data time	a hold	tCKI		Data hold from SOK0, 1. Refer to Figure 5.	4.5 to 6.0	0.1			
Serial output	time (Ser	ial clock trnal	tCKO(1)	• SO0, \$01 • SB0, \$B1	• Use a pullup/resistor (1)(C)) when set to open-drain output.	4.5 to 6.0			7/12tCYC +0.2	
Seria	time (Ser	ial clock ternal	tCKO(2)		• Data hold from SCK0, 1 • Refer to Figure 5.	4.5 to 6.0			1/3tCYC +0.2	

Pulse Input Conditions at $Ta = -30^{\circ}C$ to $+70^{\circ}C$, $V_{SS} = 0$ V 5.

Parameter	Symbol	Pins	Conditions			Ratings		Unit
				V _{DD} [V]	min	typ	max	
High/low-level pulse width	tPIH(1) tPIL(1)	• INT0, INT1 • INT2/T0IN • INT3	Interrupt acceptable Timer 0 pulse countable	4.5 to 6.0	1,8		The said of the sa	tCYC
	tPIH(2) tPIL(2)	INT3 (The noise rejection clock selected to 1/1.)	Interrupt acceptable Timer 0 pulse countable	4.5 to 6.0	2			
	tPIH(3) tPIL(3)	INT3 (The noise rejection clock selected to 1/16.)	Interrupt acceptable Timer 0 pulse countable	4.5 to 6.0	32		and the second second	
	tPIL(4)	RES	Reset acceptable	4.5 to 6.0	200	11		μs

A/D Converter Characteristics at $Ta = -30^{\circ}C_{\star}t_{0} + 70^{\circ}C_{\star}t_{0}$ 6.

			211 321	5.00° 35 (2) 35 (2)	2" 4"			
Parameter	Symbol	Pins	Condition			Ratings		Unit
				V _{DD} [V]	∮ / min	typ	max	
Resolution	N		//		g. Jed	8		bit
Absolute precision (Note 2)	ET		// 2%	4.5 to 6.0			±1/5	LSB
Conversion time	tCAD	and the second s	A/D conversion time = 16 x tCYC (ADCR2 = 0)	4,5 to 6.0	15.68 (tCYC = 0.98 μs)		65.28 (tCYC = 4.08 μs)	μs
			(Note 3) A/D conversion time = 32 × tCYC (ADCR2 = 1) (Note 3)		31.36 (tCYC = 0.98 μs)		130.56 (tCYC = 4.08 μs)	
Analog input voltage range	Vain	AN0 to AN7		4.5 to 5.5	V _{SS}		V_{DD}	V
Analog port	IAINĤ		V _{AfN} # V _{DD}	4.5 to 5.5			+1	μΑ
input current	1 _{AINL}		Vain = Vss	4.5 to 5.5	-1			

(Note 2) Quantizing error (±1/2 LSB) is ignored.

(Note 3) The conversion time is the period from execution of the instruction to start conversion to the completion of shifting the A/D converted value to the register.



7. Current Drain Characteristics at $Ta=-30^{\circ}C$ to $+70^{\circ}C$, $~V_{SS}=0~V$

Parameter	Symbol	Pins	Conditions			Ratings		Unit
				V _{DD} [V]	min	typ	max	
Current drain during basic operation (Note 4)	IDDOP(1)	VDD	FmCF = 12 MHz for ceramic resonator oscillation. FsXtal = 32.768 kHz for crystal oscillator. System clock: CF oscillator. Internal RC oscillator stopped.	4.5 to 6.0		13	26	mA
	IDDOP(2)		FmCF = 3 MHz for ceramic resonator oscillation. FsXtal = 32.768 kHz for crystal oscillator. System clock: CF oscillator. Internal RC oscillator stopped.	4.5 to 6.0°		And the state of t	14	
	I _{DDOP} (3)	A A A	FmCF = 0 Hz (when oscillator stops). FsXtal = 32.768 kHz for crystal oscillator. System clock: RC oscillator.	4.5 to 6:0		4	10	
	IDDOP(4)		PrincF = 0 Hz (when oscillator stops). FsXtal = 32.768 kr/z for crystal oscillator. System clock: crystal oscillator. Internat RC oscillator stopped.	4.5 to 6.0		4	8	

Parameter	Symbol	Pins	Conditions			Ratings		Unit
				V _{DD} [V]	min	typ	max	
Current drain at HALT mode (Note 4)	Iddhalt(1)	V _{DD}	HALT mode FmCF = 12 MHz for ceramic resonator oscillation. FsXtal = 32.768 kHz for crystal oscillator. System clock: CF oscillator. Internal RC oscillator stopped.	4.5 to 6.0		5	10	mA
	Iddhalt(2)		HALT mode FmCF = 3 MHz for ceramic resonator oscillation. FsXtal = 32.768 kHz for crystal oscillator. System clock. CF oscillator. Internal RC oscillator stopped.	4.5 to 6.0		2.2	4.6	
	Iddhalt(3)	and the state of t	HALT mode FmCF = 0 Hz (when oscillator stops). FsXtal = 32.768 kHz for crystal oscillator System clock RC oscillator	4.5 to 6:0		550	1100	μΑ
	IDDHALT(4)		HALT mode FmGF ≥ 0 Hz (when oscillator stops). FsXtal = 32,768 kHz for erystal oscillator. System clock: crystal oscillator. Internal RC oscillator stopped.	4.5 to 6.0		25	100	
Current drain at HOLD mode (Note 4)	I _{DDHOŁD} (1)	Vee	HOLD mode	4.5 to 6.0		0.05	30	
(14010 4)	/ Iddhold(2)			2.5 to 4.5		0.02	20	

(Note 4) The currents of output transistors and pull-up transistors are ignored.

Table 1. Ceramic Resonator Oscillation Guaranteed Constants (Main clock)

Oscillation type	Supplier	Oscillator	C1	C2
12 MHz ceramic resonator	Murata	CSA12.0MTZ	33 pF	33 p.F.
oscillation		CST12.0MTW	on c	hip
	Kyocera	KBR-12.0M	33 pF	33 pF
3 MHz ceramic resonator	Murata	CSA3.00MG040	100 pF	/100 pF
oscillation		CST3.00MGW040	on c	hip
	Kyocera	KBR-3.0MS	47 pF	47 pF

[•] For both C1 and C2, the K rank (±10%) and SL characteristics must be used.

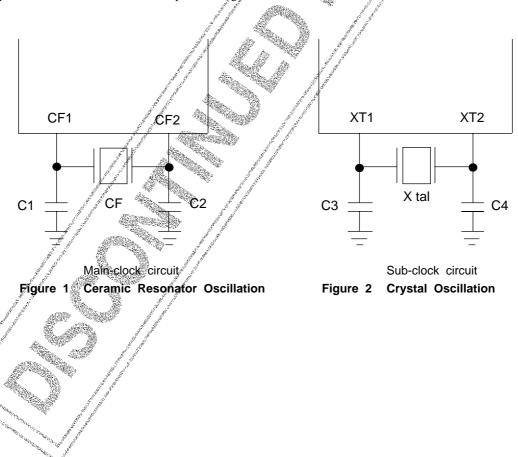
Table 2. Crystal Oscillaion Guaranteed Constants (Sub-clock)

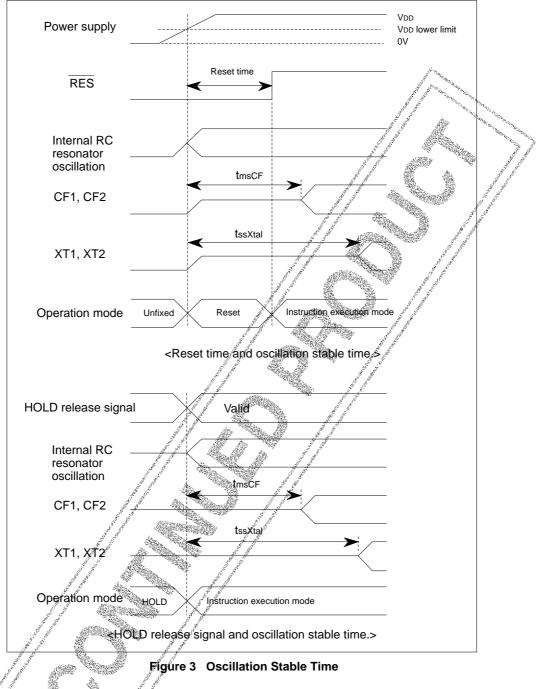
Oscillation type	Supplier	Oscillator C3 C4
32.768 kHz crystal oscillation	Kyocera	KF-38G-13P0200 18 pF √18 pF

[•] For both C3 and C4, the J rank ($\pm 5\%$) and CH characteristics must be used. (If high precision is not necessary, use K rank ($\pm 10\%$) and SE characteristics.)

Notes • Since the circuit pattern affects the oscillation frequency, place the oscillation-related parts as close to the oscillation pins as possible with the shortest possible pattern length.

• If you use other oscillators herein, we provide no guarantee for the characteristics.





RRES

CRES

The values of Cres and Rres should be determined such that reset time is at least 200 µs, measured from the moment the power exceeds the VDD lower limit.

Figure 4 Reset Circuit

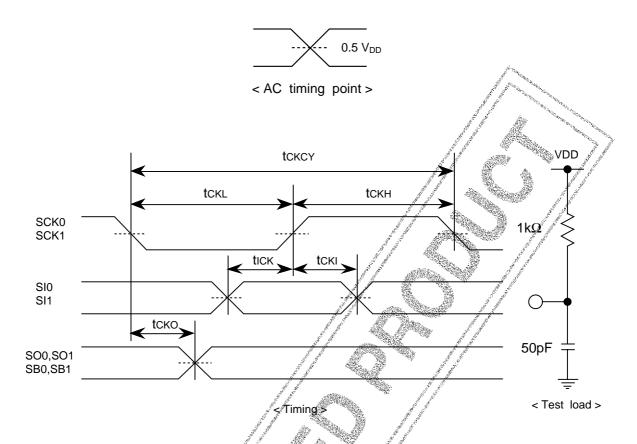
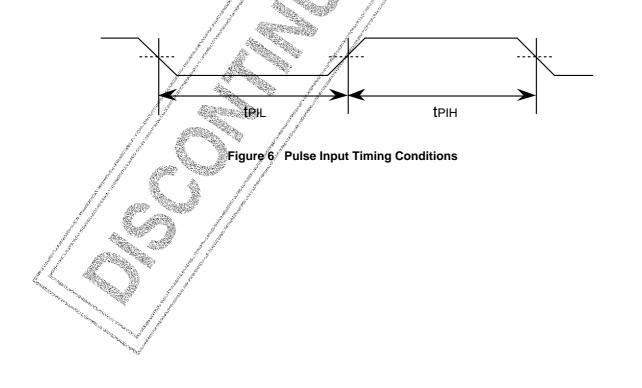


Figure 5 Serial Input/Output Test Conditions

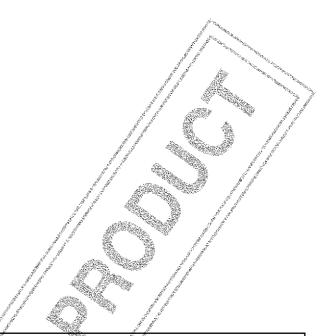


Usage Notes

- The construction of the one-time programmable microcontroller with a blank built-in PROM makes it impossible for Sanyo to completely factory-test it before shipping. To prove reliability of the programmed devices, the screening procedure shown in the following figure should always be followed.
- It is not possible to perform a writing test on the blank PROM. 100% yield, therefore, cannot be guaranteed.
- Ensure dry packaging
 The environment must be held at a temparature of 30°C or less and a humidity level of 70% or less.
- After opening the packing
 The preparation procedures shown in the following figure should always be followed prior to mounting the packages on the substrate. After opening the packing, a controlled environment must be maintained until soldering.

 The environment must be held at a temperature of 30°C or less and a humidity level of 70% or less. Please solder within 96 hours.

a. Shipping with a blank PROM (Data to be programmed by customer) QFP DIP Programming and Programming and verifying verifying Recommended process of screening Recommended process of screening Heat-soak Heat-soak $150 \pm 5^{\circ}\text{C}$, 24 $^{+1}_{-0}$ Hr 150 ± 5°C. 24 Program reading test Program reading test Mounting Mounting b. Shipping with programmed PROM (Data programmed by Sanyo) DIP QFP Mounting Mounting



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